

**N-Ch MOSFET** 

### **General Description**

The WSF2048 is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSF2048 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

## Absolute Maximum Ratings

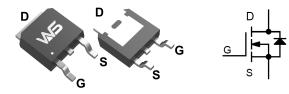
### **Product Summery**

BVDSS	RDSON	ID
20V	6.2mΩ	40A

#### Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

#### **TO-252 Pin Configuration**



Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	20	V
V <sub>GS</sub>	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V	40	А
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V	28	А
I <sub>DM</sub>	Pulsed Drain Current	80	А
EAS	Single Pulse Avalanche Energy	150	mJ
I <sub>AS</sub>	Avalanche Current	40	А
P₀@T₀=25℃	Total Power Dissipation <sup>4</sup>	60	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-ambient (Steady State)		62	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient (t ≤10s)		25	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case		3.8	°C/W



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### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to $25^\circ C$ , I <sub>D</sub> =1mA		0.028		<b>V/°</b> C
	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =25A		6.2	10	mΩ
R <sub>DS(ON)</sub>		V <sub>GS</sub> =2.5V , I <sub>D</sub> =10A		9.1	12	
V <sub>GS(th)</sub>	Gate Threshold Voltage		0.5	0.75	1.2	V
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250$ uA		-6.16		mV/℃
1	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C			1		
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A	10			S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0	3.1	Ω
Qg	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		15		nC
Q <sub>gs</sub>	Gate-Source Charge			1.8		
Q <sub>gd</sub>	Gate-Drain Charge			2.8		
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω I <sub>D</sub> =15A		4.5		
Tr	Rise Time			9.2		- ns
T <sub>d(off)</sub>	Turn-Off Delay Time			18.7		
T <sub>f</sub>	Fall Time			3.3		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		1100		
C <sub>oss</sub>	Output Capacitance			162		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			105		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	$V_G=V_D=0V$ , Force Current			30	А
V <sub>SD</sub>	Diode Forward Voltage	$V_{GS}\text{=}0V$ , $I_{S}\text{=}1A$ , $T_{J}\text{=}25^{\circ}\!\mathbb{C}$			1.2	V
t <sub>rr</sub>	Reverse Recovery Time			18		nS
Qrr	Reverse Recovery Charge	IF=20A , dI/dt=100A/ $\mu s$ , T $_{ m J}$ =25 $^\circ { m C}$		9.5		nC

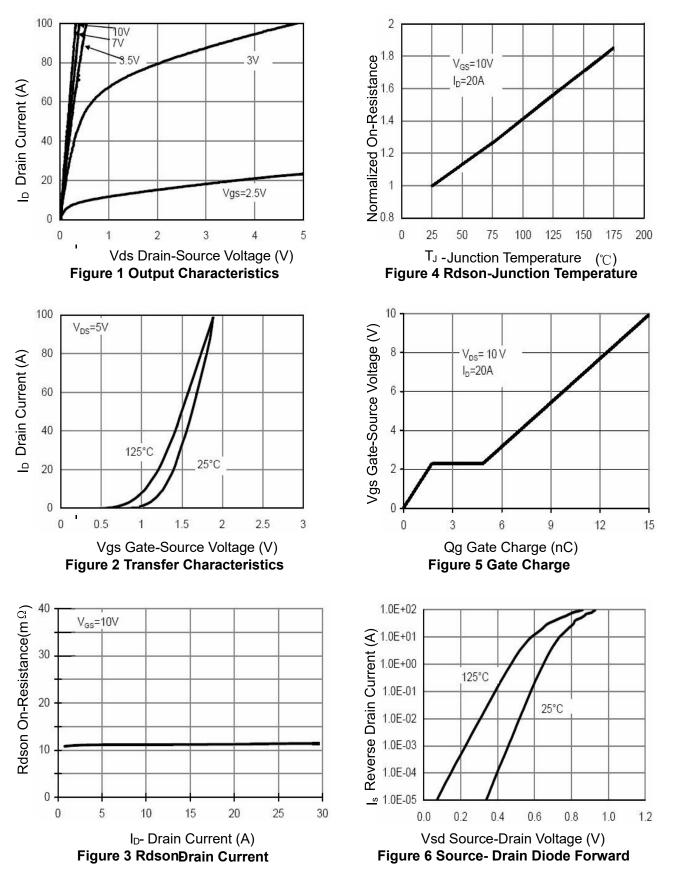
#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- **5.**  $E_{AS}$  condition : Tj=25°C,  $V_{DD}$ =10V,  $V_{G}$ =10V, L=0.5mH, Rg=25 $\Omega$ ,



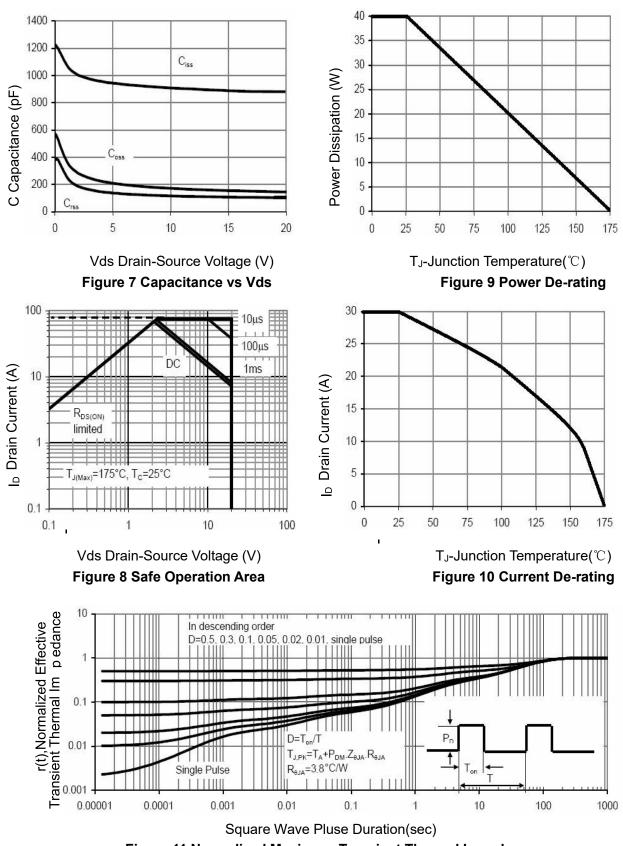
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## **Typical Characteristics**





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